

**Chip structure with bumps and testing pads**

Appl. No. : 10/730,834 Confirmation No. 5204  
Applicant : Nick Kuo,  
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TC/A.U. : 2826  
Examiner : ANDUJAR, LEONARDO  
Docket No. : MEGP0033USA0  
Customer No. : 27765

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**AMENDMENT**

Sir:

- 5 In response to the Office action of July 05, 2006, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

- 10 **Remarks/Arguments** begin on page 11 of this paper.